



IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Certificate of Approval Independent Testing Laboratory

IECQ Certificate No.:	IECQ-L NSAIUS 15.0003	Issue No.:	1	Status:	Current
Supersedes:		Issue Date:	2015/09/17	Org Issue:	2015/09/17
CB Certificate No.:	1.72.0031	Expiration:	2016/07/24		

Integrated Service Technology Inc.

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Taiwan

The organization, facilities and procedures have been assessed and found to comply with the applicable requirements for Independent Testing Laboratory organization approval, in support of the IECQ system, which is in accordance with the Basic Rules IECQ 01 and Rules of Procedure IECQ 03-6 "Independent Testing Laboratory Assessment Program Requirements" of the IEC Quality Assessment System for Electronic Components (IECQ) and applicable requirements of ISO/IEC 17025: 2005 for the testing of electronic components under the IECQ.





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Scope:

1. Environmental and Reliability Testing

(JEDEC JESD47, JESD22 Series, JESD89-1/2/3, JESD201, JS-001, JS002, J-STD-020, J-STD-035, JESD78, JP001, J-STD-002, J-STD-003, JIS K5600-5-4, AEC-Q100 Series, AEC-Q101 Series, AEC-Q200 Series, AEC-Q005, ASTM Series, EIAJ ED-4701 Series / EIA 364 Series, EIAJ-4702 Series, SAE J1752-2 / J1752-3, IEC 62137-1-2, IEC 61000-4-2, IEC60068 Series / IPC-TM-650, IPC-A-600, IPC-A-610, IPC-6012, IPC-9708, ANSI/ESDA STM5.1/5.2/5.3, MIL-STD-810 , MIL-STD-883 , MIL-STD-750 , MIL-STD-202 , MILSTD-1344)

Including tests of:
File No 1.72.0031
&C

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Preconditioning of non-hermetic Surface Mount Device prior to reliability testing(PC), Steady State Bias Temperature and Humidity Bias Life(THB/H3TRB), Highly Accelerated Temperature and Humidity Stress Test (HAST, JESD22A-110), Accelerated Moisture Resistance-Unbiased Autoclave(AC/PCT), Accelerated Moisture Resistance-Unbiased HAST(UHAST), Temperature Cycling(TCT), Thermal Shock(TST), Power and Temperature Cycling(PTC), High Temperature Storage Life(HTSL), Low Temperature Storage Life(LTSL), Temperature Bias and Operating Life (HTOL/LTOL/HTGB/HTRB/HTFB/ELFR/IOL, JESD22-A108/AECQ100-008), Non-Volatile Memory Program/Erase Endurance, Data Retention and Operating Life Test (Endurance/Data Retention), Wire bonding and solder ball integrity test(WBS/WBP/SBS), Solderability(SD), Physical Dimensions(PD), Lead Integrity(LI), Bond Strength, Electrostatic discharge test(HBM/MM/CDM), Latch-up(LU), IC EMC test(EMC), Gate Leakage test(GL), Soft Error Rate(SSER/ASER), Short Circuit(SC), PB-Free test(LF), Gross and fine leak(GFL), Lead Torque(LT), Die Shear(DS), External Visual(EV), Terminal Strength(TS), Twist, Durability, Push/Pull, Abrasion Resistance(RCA), Film Hardness by Pencil, Resistance to Solvents(RTS), Resistance to Soldering Heat(RSH), Flame Retardance, Flammability, Mechanical Shock(MS), Vibration Variable Frequency (VVF), Dielectric Integrity(DI), Electrical Migration(EM), Salt, Gas Corrosion.

2. Failure analysis and material analysis of semiconductor integrated circuits, electronic components and PCB/PCBA, including FIB (Focused Ion Beam), Electrical Analysis, Sample Preparation (Decap, Delayer, Cross-section, COB, etc), NDE (Non-destructive Engineering), Physical & Chemical Analysis (Including Hazardous Substances) and IC package.

3. 2nd Level Integration Platform Service

(JESD22 Series, AEC-Q200 Series, IPC-9701, IPC-9704, EIAJ-4702 Series, IEC60068 Series, SEMI G86-03, IPC-7525B, IPC-610 Series)

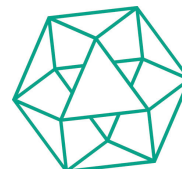
Including test of :

SMT and 2nd reliability Services: Temperature Cycling (IPC 9701/JESD22 A104), Board Level Drop (JESD22 B104/B111), Shock Test, Vibration Test, Bending Test (Cyclic bend, Monotonic bend (IPC 9702), Chip and Die Strength, Pull/Push Test and SMT and PCBA test (Cold ball pull test, wire pull test, ball shear test and hot bond pull test, Stencil Design, Solderability(SD)

Approved by Certification Body (CB): National Standards Authority of Ireland, Inc.

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Authorized person:
Kevin D Mullaney



NSAI

Sponsoring Member Body



The validity of this approval is maintained through on-going surveillance inspections.
Note: This approval may be suspended or withdrawn in accordance with the Rules of Procedure of the IECQ.

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The Status and authenticity of this approval may be verified by visiting the www.iecq.org